

### **AMENDMENTS TO THE CLAIMS**

**Claims 1-37 (Cancelled).**

**Claim 38 (New)** A method for filling a metal into fine recesses in a surface of a substrate, comprising:

providing a substrate having fine recesses covered with a seed layer in a surface of the substrate;

reinforcing the seed layer by contacting the surface of the seed layer in a first plating liquid having ions of a metal and a complexing agent; and

filling said fine recesses with the metal by electroplating a surface of the reinforced seed layer with contacting the substrate in a second plating liquid;

washing a surface of the metal on the substrate with water or washing liquid comprising water; and

removing the metal on an edge portion of the substrate by supplying an etching liquid to a surface of the metal on the edge portion of the substrate;

wherein the washing the surface of the metal is performed prior to the removing of the metal on the edge portion of the substrate.